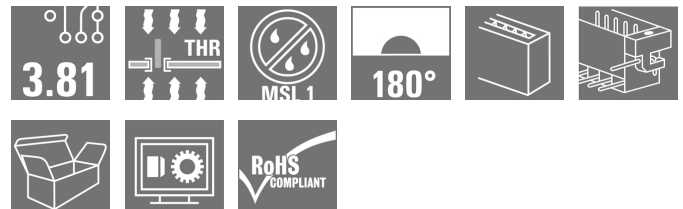


BCL-SMT 3.81/10/180LFI 1.5SN BK BX**Weidmüller Interface GmbH & Co. KG**

Klingenbergstraße 26

D-32758 Detmold

Germany

www.weidmueller.com**Product image**

The inverted BCL-SMT socket block for the PCB offers three significant advantages:

- The BCL-SMT offers touch-safe security on the PCB which makes it ideal for live, current-carrying outputs.
- The BCL-SMT widens the range of applications with board-to-board connections between component assemblies.
- The BCL-SMT is reflow-compatible and can be seamlessly integrated into the automatic assembly and soldering process.

Two outlet directions give you a choice of position and thus more design flexibility.

- 180° standing
- 90° recumbent

Two housing variants are available for the BCL-SMT:

- Without flange
- With inverted solder flange ("LFI", with nut)
 - Fastened to PCB without additional screw
 - Fastened with screw to the SCZ FI

Weidmüller's 3.81-mm-pitch (0.15 inch) plug-in connectors are compatible with the layouts of customary connectors and offer space for labelling and coding.

General ordering data

Version	PCB plug-in connector, female header, Solder flange inverted, THT/THR solder connection, 3.81 mm, Number of poles: 10, 180°, Solder pin length (l): 1.5 mm, tinned, black, Box
Order No.	1029350000
Type	BCL-SMT 3.81/10/180LFI 1.5SN BK BX
GTIN (EAN)	4032248758647
Qty.	50 pc(s).
Product data	IEC: 320 V / 17.5 A UL: 300 V / 10 A
Packaging	Box

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Technical data**Dimensions and weights**

Net weight	4.96 g
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System specifications

Product family	OMNIMATE Signal - series BC/SC 3.81		
Type of connection	Board connection		
Mounting onto the PCB	THT/THR solder connection		
Pitch in mm (P)	3.81 mm		
Pitch in inches (P)	0.15 inch		
Outgoing elbow	180°		
Number of poles	10		
Number of solder pins per pole	2		
Solder pin length (l)	1.5 mm		
Solder pin length tolerance	0 / -0,02 mm		
Solder pin dimensions	d = 0.8 mm		
Solder pin dimensions = d tolerance	+0,05 / -0,05 mm		
Solder eyelet hole diameter (D)	1.2 mm		
Solder eyelet hole diameter tolerance (D)	+ 0,1 mm		
Outside diameter of solder pad	1.9 mm		
Template aperture diameter	1.6 mm		
L1 in mm	34.29 mm		
L1 in inches	1.35 inch		
Number of rows	1		
Pin series quantity	1		
Touch-safe protection acc. to DIN VDE 57 106	Safe from finger touch		
Touch-safe protection acc. to DIN VDE 0470	IP 20		
Volume resistance	≤5 mΩ		
Can be coded	Yes		
Plugging force/pole, max.	9.5 N		
Pulling force/pole, max.	6 N		
Tightening torque	Torque type	Mounting screw, PCB	
	Usage information	Tightening torque	min. 0.1 Nm
			max. 0.15 Nm
		Recommended screw	Part number PTSC KA 2.2X4.5 WN1412

Material data

Insulating material	LCP GF	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	IIIa
Comparative Tracking Index (CTI)	≥ 175	Moisture Level (MSL)	1
UL 94 flammability rating	V-0	Contact material	Copper alloy
Contact surface	tinned	Layer structure of solder connection	1...3 µm Ni / 2...4 µm Sn matt
Layer structure of plug contact	1...3 µm Ni / 2...4 µm Sn matt	Storage temperature, min.	-40 °C
Storage temperature, max.	70 °C	Operating temperature, min.	-50 °C
Operating temperature, max.	120 °C	Temperature range, installation, min.	-25 °C
Temperature range, installation, max.	120 °C		

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Technical data**Rated data acc. to IEC**

tested acc. to standard	IEC 60664-1, IEC 61984	Rated current, min. number of poles (Tu=20°C)	17.5 A
Rated current, max. number of poles (Tu=20°C)	15.4 A	Rated current, min. number of poles (Tu=40°C)	17.5 A
Rated current, max. number of poles (Tu=40°C)	13.8 A	Rated voltage for surge voltage class / pollution degree II/2	320 V
Rated voltage for surge voltage class / pollution degree III/2	160 V	Rated voltage for surge voltage class / pollution degree III/3	160 V
Rated impulse voltage for surge voltage class/ pollution degree II/2	2.5 kV	Rated impulse voltage for surge voltage class/ pollution degree III/2	2.5 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	2.5 kV	Short-time withstand current resistance	3 x 1s with 76 A

Rated data acc. to CSA

Rated voltage (Use group B / CSA)	300 V	Rated voltage (Use group C / CSA)	50 V
Rated current (Use group B / CSA)	11 A	Rated current (Use group C / CSA)	11 A

Rated data acc. to UL 1059

Institute (cURus)		Certificate No. (cURus)	E60693
Rated voltage (Use group B / UL 1059)	300 V	Rated voltage (Use group D / UL 1059)	300 V
Rated current (Use group B / UL 1059)	10 A	Rated current (Use group D / UL 1059)	10 A
Reference to approval values	Specifications are maximum values, details - see approval certificate.		

Packing

Packaging	Box	VPE length	25 mm
VPE width	120 mm	VPE height	210 mm

Classifications

ETIM 6.0	EC002637	ETIM 7.0	EC002637
ECLASS 9.0	27-44-04-02	ECLASS 9.1	27-44-04-02
ECLASS 10.0	27-44-04-02	ECLASS 11.0	27-46-02-01

Important note

IPC conformity	Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.		
Notes	- Rated current related to rated cross-section & min. No. of poles. - P on drawing = pitch - Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards. - Long term storage of the product with average temperature of 50 °C and average humidity 70%, 36 months		

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www.weidmueller.com**Technical data****Approvals**

Approvals



ROHS Conform

UL File Number Search E60693

DownloadsApproval/Certificate/Document of
Conformity[Declaration of the Manufacturer](#)

Engineering Data

[STEP](#)

Engineering Data

[EPLAN, WSCAD](#)

BCL-SMT 3.81/10/180LFI 1.5SN BK BX

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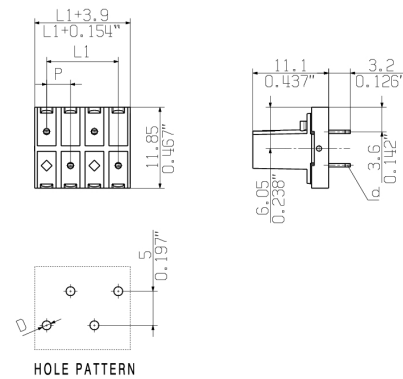
www.weidmueller.com

Drawings

Product image



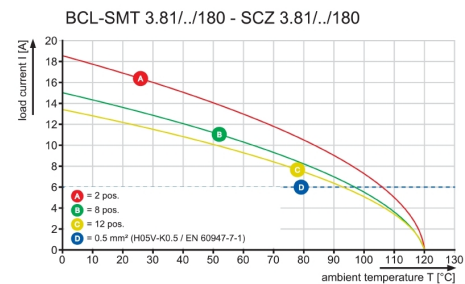
Dimensional drawing



Graph



Graph



WEITERGABE SOWIE VERVIELFÄLTIGUNG DIESES DOKUMENTS, VERWERTUNG UND MITTEILUNG SEINES INHALTS SIND VERBOTEN, SOWEIT NICHT AUSDRUECKLICH GESTATET.
ZUWIDERHANDLUNGEN VERPFLICHTEN ZU SCHADENERSATZ. ALLE RECHTE FUER DEN FALL DER PATENT-, GEBRAUCHSMUSTER- ODER GESCHMACKSMUSTEREINTRAGUNG VORBEHALTEN.
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BCL-SMT 3.81/.../180 1.5...



NOTE:

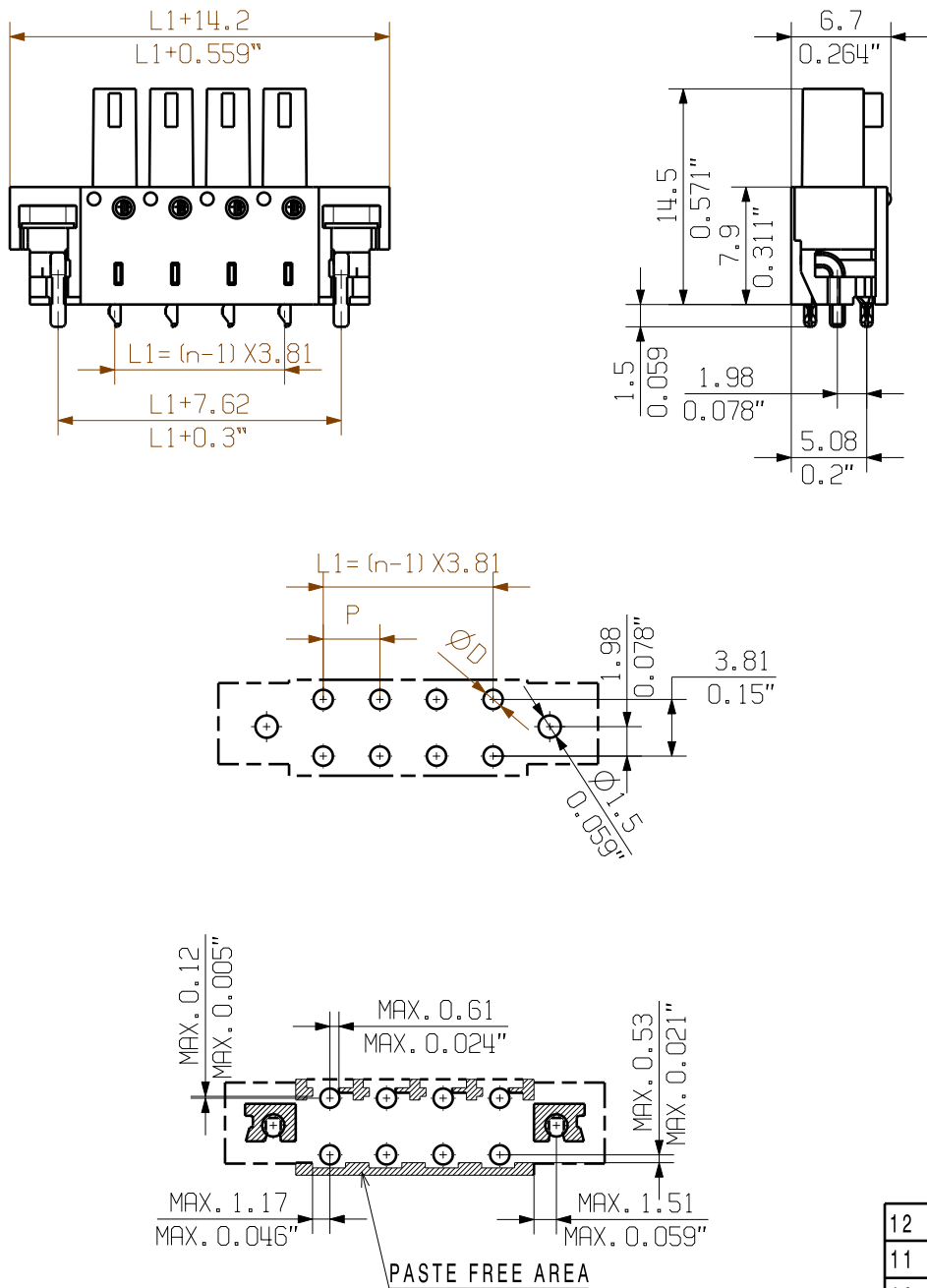
n=NO OF POLES
P=PITCH

KUNDENZEICHNUNG
CUSTOMER DRAWING

For the mounting of PCBs, it should be noted that the rated data given in the catalogue relates only to the connection elements. The necessary creepage and clearance paths must be observed in connection with the respective applicant in accordance to VDE 0110. The current-carrying capacity and pitch tolerance is to be determined according to DIN IEC 326 part 3 very fine.

Weidmüller connectors are tested to the DIN VDE 0627 standard, and are valid for its field of application. Provided that the connectors are used to the intended purpose, all requirements with respect to the occurring of electrical, mechanical, thermic and corrosive stress will be satisfied.

BCL-SMT 3.81/.../180LFI 1.5...



12	41.91	1.650
11	38.10	1.500
10	34.29	1.350
9	30.48	1.200
8	26.67	1.050
7	22.86	0.900
6	19.05	0.750
5	15.24	0.600
4	11.43	0.450
3	7.62	0.300
2	3.81	0.150
n	L1 [mm]	L1 [inch]

				CAT.NO.:.	
62605/5 28.08.12 SHI_S		00			
MODIFICATION					
		DATE		NAME	
DRAWN		19.02.2008		SHI_S	
RESPONSIBLE				XU_S	
CHECKED		29.08.2012		ZHOU_N	
APPROVED				XU_S	
SCALE: 2/1					
SUPERSEDES: .					
SUPERSEDED BY: .					

Weidmüller 		C 40405 	
DRAWING NO.		ISSUE NO.	
BCL-SMT 3.81/.../180...1.5... LOETANSCHLUSS BUCHSENLEISTE SOLDER CONNECTION SOCKET CONNECTOR			
PRODUCT FILE: BCL-SMT 3.81		7084	

Recommended wave soldering profiles

Weidmüller Interface GmbH & Co. KG
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Germany
Fon: +49 5231 14-0
Fax: +49 5231 14-292083
www.weidmueller.com

Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

We reserve the right to make technical changes.

Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.